

HOSTAFORM[®] MT[®]8R02 HOSTAFORM®

Hostaform® MT®8R02 is an improved wear performance grade targeted at injection molding grade with a molecular weight for excellent moldability and optimum properties in demanding applications.

Hostaform® MT®8R02 is a special grade developed for medical industry applications and complies with:

- CFR 21 (177.2470) of the Food and Drug Administration (FDA) and is listed in the Drug Master File (DMF 11559) and the Device Master File (MAF 1079)
- the corresponding EU and national registry regulatory requirements
- biocompatibility in tests corresponding to USP <88> Class VI/ISO 10993
- low residual monomers
- no animal-derived constituents

Product information

Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties Melt volume-flow rate Temperature Load	8.5 190 2.16		ISO 1133
Typical mechanical properties		C C	
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Charpy notched impact strength, 23°C Poisson's ratio [C]: Calculated	9 30	MPa %	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 179/1eA
Thermal properties			
Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa	165 82	°C °C	ISO 11357-1/-3 ISO 75-1/-2
Physical/Other properties			
Density	1400	kg/m³	ISO 1183
Injection			
Drying Recommended Drying Temperature Drying Time, Dehumidified Dryer Processing Moisture Content Melt Temperature Optimum Min. melt temperature Max. melt temperature Screw tangential speed Mold Temperature Optimum	no 100 3 - 4 ≤0.2 190 180 200 ≤0.3 100	h °C °C °C m/s	

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(+) **18816996168** Ponciplastics.com



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Min. mould temperature
Max. mould temperature
Hold pressure range
Back pressure
Ejection temperature

Characteristics

Injection Moulding
Pellets
Release agent
Low wear / Low friction

Additional information

Processing Notes

80 120	°C °C
	MPa
4	MPa
134	°C
	120 120 4

Pre-Drying

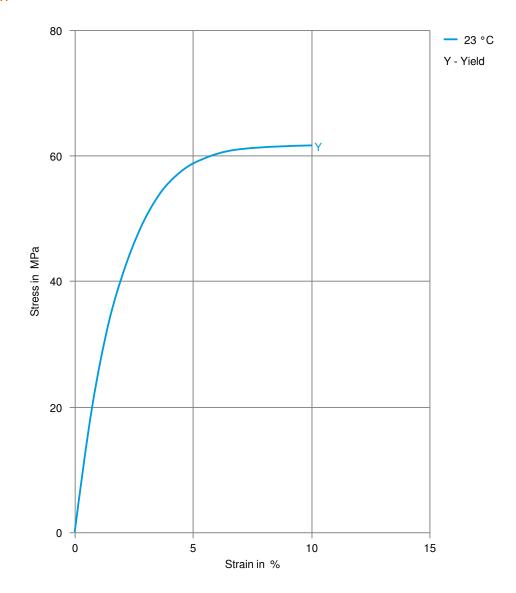
Drying is not normally required. If material has come in contact with moisture through improper storage or handling, drying may be necessary to prevent splay and odor problems.





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Stress-strain

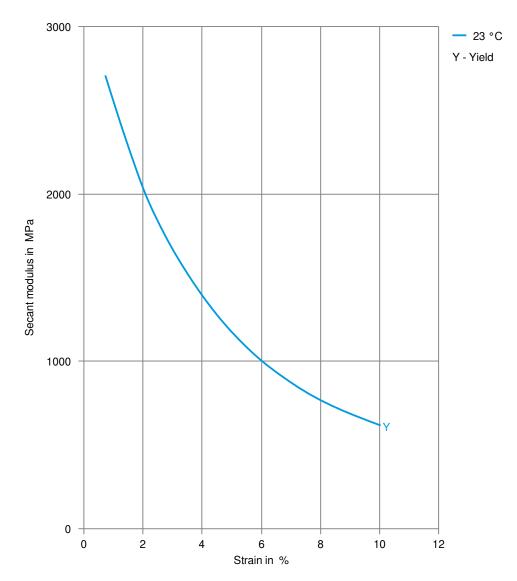






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Secant modulus-strain

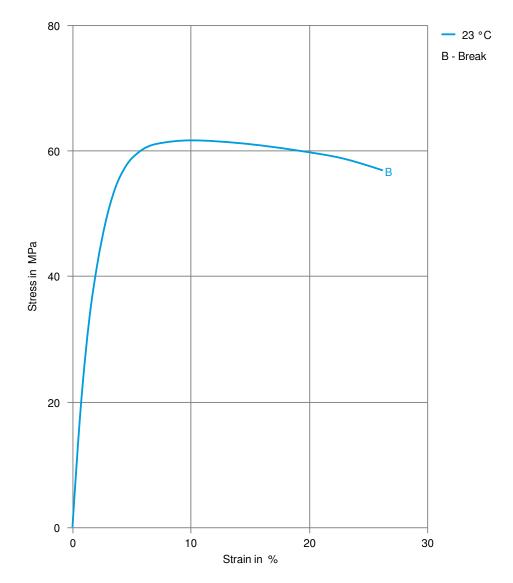






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Stress-strain, 50mm/min

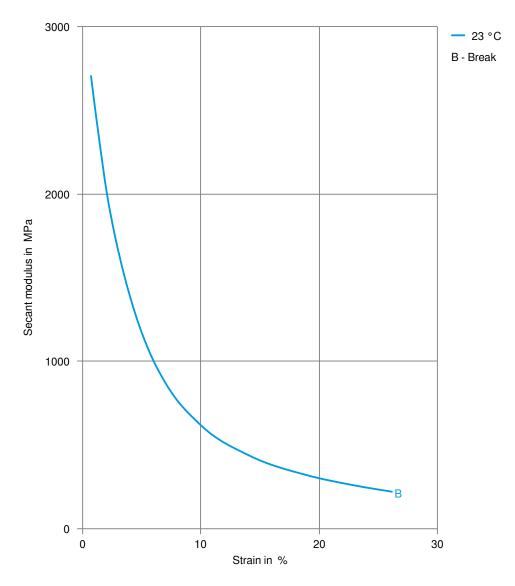






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Secant modulus-strain, 50mm/min



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